

PATENT NUMBER

U.S. **UTILITY** Patent Application

12W Q.I.P.E.
SCANNED Q.A. 653

PATENT DATE

APPLICATION NO.	CONT/PRIOR	CLASS	SUBCLASS	ART UNIT	EXAMINER
09/632910	D F	257 ⁴³⁵	616	2816 ³⁸²⁷	CHAMBERS

APPLICANTS

Kohei Tatemai
Kenji Shimokawa
Eiji Hashino

TITLE

Semiconductor device provided with low melting point metal bumps
and process for producing same

PTO-2040
12/89

ISSUING CLASSIFICATION

[illegible]☐ Continued on Issue Slip Inside File Jacket

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS		CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed. <input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____ 	_____ (Assistant Examiner)		NOTICE OF ALLOWANCE MAILED 	
	_____ (Date)		ISSUE FEE Amount Due Date Paid	
<input type="checkbox"/> The terminal ____months of this patent have been disclaimed.	_____ (Primary Examiner)		ISSUE BATCH NUMBER	
_____ (Legal Instruments Examiner)		_____ (Date)		
WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368. Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.				

Form **PTO-436A**
(Rev. 6/99)

FILED WITH: ☐ DISK (CRF) ☐ FICHE ☐ CD-ROM
(Attached in pocket on right inside flap)